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2821

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Applicant: Salman Akram § Group Art Unit: 2827
Serial No.: 09/853,111 §
Filed: May 10, 2001 §
For: Method of Fabricating Mounted §
Multiple Semiconductor Dies In §
A Package (As Amended) §

Examiner: A. Chambliss
Atty. Dkt. No.: MCT.0012D1US
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Commissioner for Patents
Washington DC 20231

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REPLY TO PAPER NO. 4

Sir:

In response to the office action mailed April 3, 2002, please amend the above-referenced patent application as follows:

IN THE CLAIMS

Please amend claim 15 as follows:

15 (Twice Amended). A method for mounting multiple semiconductor dies on a single leadframe having fingers, comprising:
stacking at least two semiconductor dies having substantially the same rectangular dimensions on top of one another such that one of said dies is mounted on top of the leadframe fingers and the other of said dies is mounted on the die mounted on the leadframe fingers; and wire bonding each of said semiconductor dies to the leadframe.

Please amend claim 32 as follows:

32 (Amended). A method for mounting multiple semiconductor dies on a single leadframe having fingers, comprising:

Date of Deposit: 04-25-02
I hereby certify under 37 CFR 1.8(a) that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage on the date indicated above and is addressed to the Commissioner for Patents, Washington DC 20231.
Cynthia L. Hayden
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